

CURRENTLY PENDING CLAIMS

1-62. (Cancelled)

63. A wafer having a surface, the surface comprising:
a plurality of elongated strips of polysilicon; and
a plurality of elongated strips of dielectric material, the strips of dielectric
material alternating with the strips of polysilicon,
wherein the surface has been planarized by chemical mechanical planarization,
and
wherein a first percentage of total wafer surface area that is polysilicon is less
than or equal to 70 percent.

64. The wafer of claim 63 wherein the first percentage is greater than 50 percent.

65. The wafer of claim 63 wherein the first percentage is less than or equal to 60 percent.

66. The wafer of claim 65 wherein the first percentage is greater than 50 percent.

67. The wafer of claim 63 wherein the first percentage is less than or equal to 50 percent.

68. The wafer of claim 63 wherein the strips of polysilicon have a shortest dimension less
than or equal to 500 microns.

69. The wafer of claim 68 wherein the strips have a shortest dimension between 0.25 and
500 microns.

70. The wafer of claim 63 wherein the surface of the wafer can attract enough water to
wet sufficiently allowing removal of residual particles therefrom.